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- Assembly Assistance
- Die handling consultancy
- Hi-Rel die qualification
- Hot & Cold die probing
- Electrical test & trimming

Distributed Product Support

- Customised Pack Sizes / Qtys
- Support for all industry recognised supply formats:
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  - Gel Pak
  - Tape & Reel
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- 100% Visual Inspection
  - MIL-STD 883 Condition A
  - MIL-STD 883 Condition A
- On-site failure analysis
- Bespoke 24 Hour monitored storage systems for secure long term product support
- On-site failure analysis

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For price, delivery and to place orders

HMC486

Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED

www.analog.com

www.hittite.com

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v03.0109

HMC486

GaAs PHEMT MMIC 2 WATT POWER AMPLIFIER, 7 - 9 GHz

Typical Applications

The HMC486 is ideal for use as a power amplifier for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios
- Test Equipment & Sensors
- Military End-Use
- Space

Features

Saturated Output Power: +34 dBm @ 24% PAE

Output IP3: +40 dBm

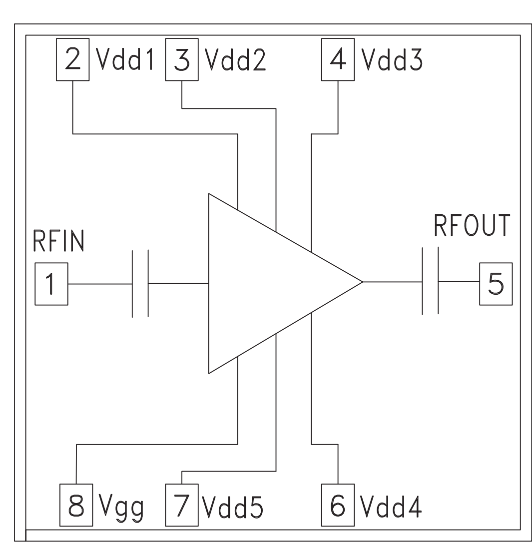
Gain: 26 dB

DC Supply: +7 V @ 1300 mA

50 Ohm Matched Input/Output

Die Size: 2.51 x 2.51 x 0.1 mm

Functional Diagram



General Description

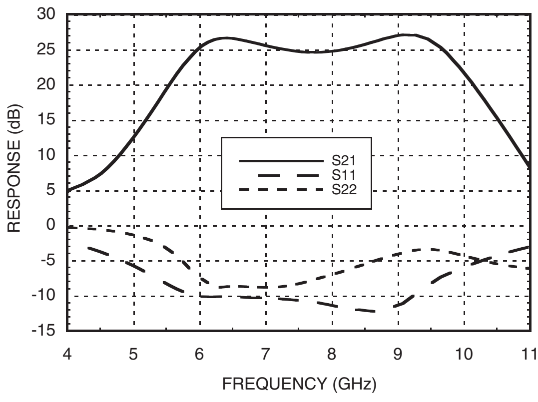
The HMC486 is a high dynamic range GaAs PHEMT MMIC 2 Watt Power Amplifier which operates from 7 to 9 GHz. This amplifier die provides 26 dB of gain, +34 dBm of saturated power and 24% PAE from a +7V supply voltage. Output IP3 is +40 dBm typical. The RF I/Os are DC blocked and matched to 50 Ohms for ease of integration into Multi-Chip-Modules (MCMs). All data is taken with the chip in a 50 ohm test fixture connected via 0.025mm (1 mil) diameter wire bonds of minimal length 0.31mm (12 mils).

Electrical Specifications, T_A = +25° C, Vdd = +7V, Idd = 1300 mA*

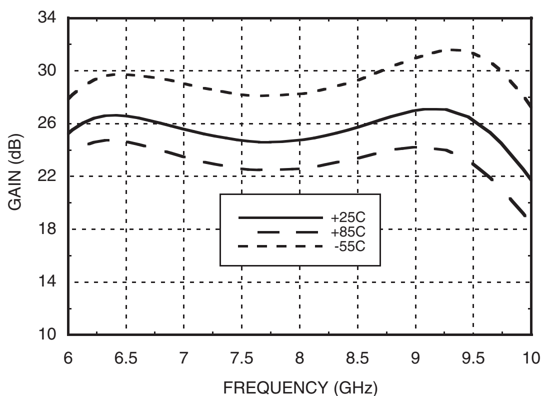
Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range		7 - 8			8 - 9		GHz
Gain	22	25		23	26		dB
Gain Variation Over Temperature		0.04	0.06		0.04	0.06	dB/ °C
Input Return Loss		11			12		dB
Output Return Loss		8			6		dB
Output Power for 1 dB Compression (P1dB)	30	33		30.5	33.5		dBm
Saturated Output Power (Psat)		33.5			34		dBm
Output Third Order Intercept (IP3)		40			38		dBm
Noise Figure		6.5			7		dB
Supply Current (Idd)		1300			1300		mA

** Adjust Vgg between -2 to 0V to achieve Idd= 1300 mA typical.*

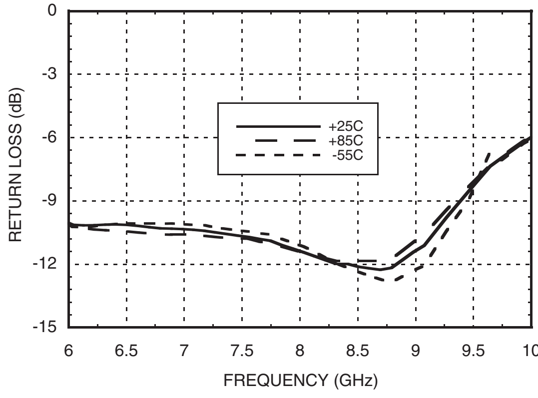
Broadband Gain & Return Loss



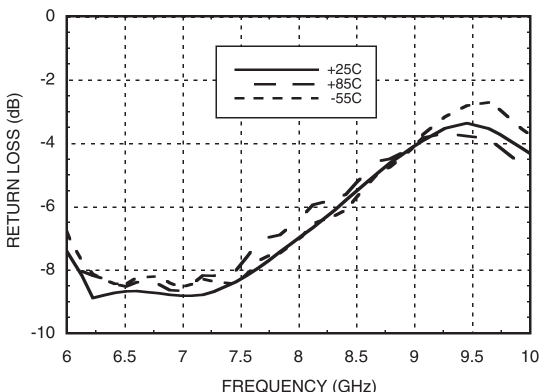
Gain vs. Temperature



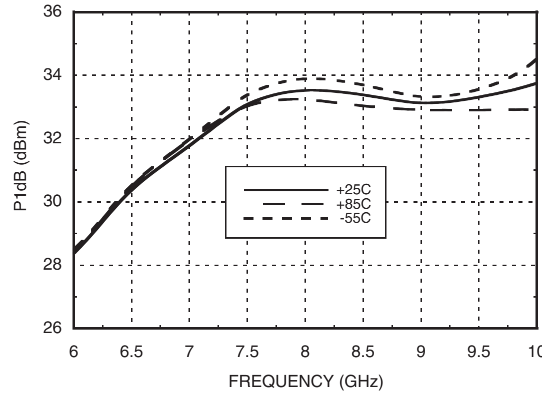
Input Return Loss vs. Temperature



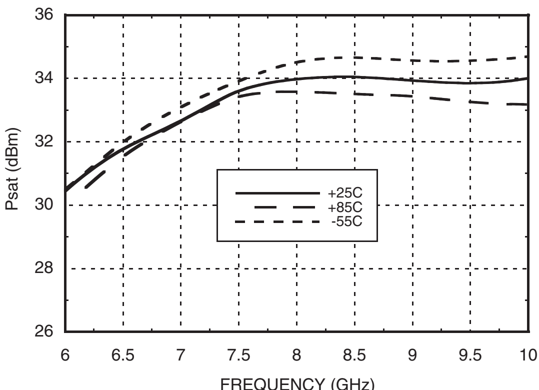
Output Return Loss vs. Temperature



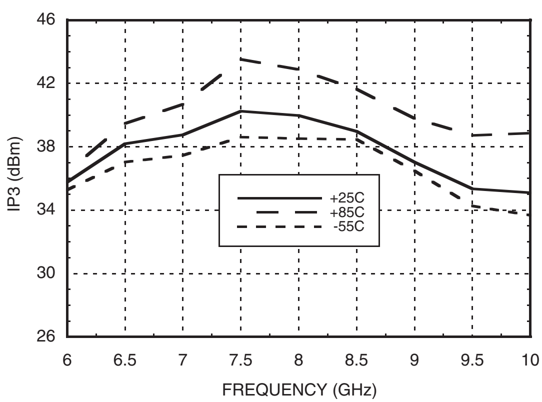
Output P1dB vs. Temperature



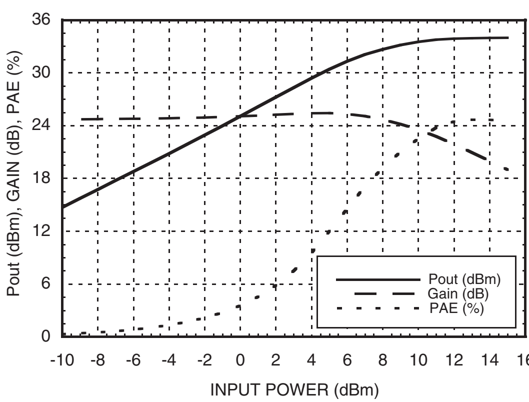
Output Psat vs. Temperature



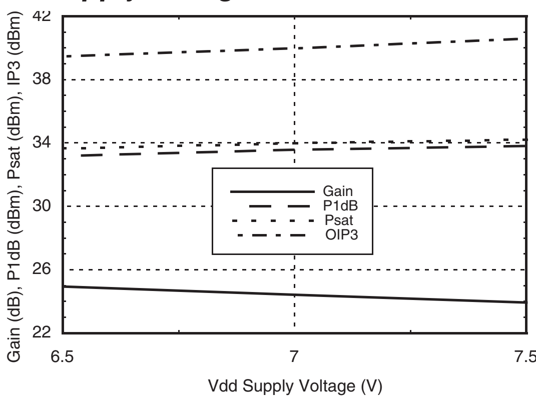
Output IP3 vs. Temperature



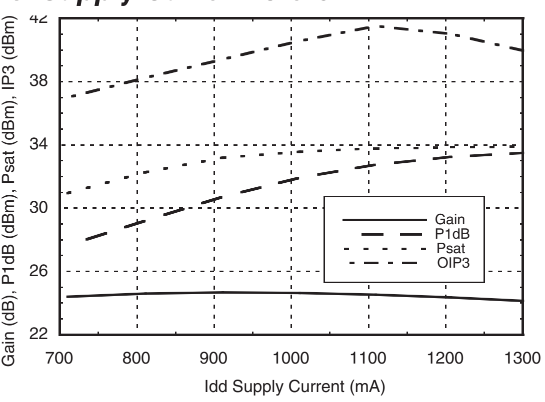
Power Compression @ 8 GHz



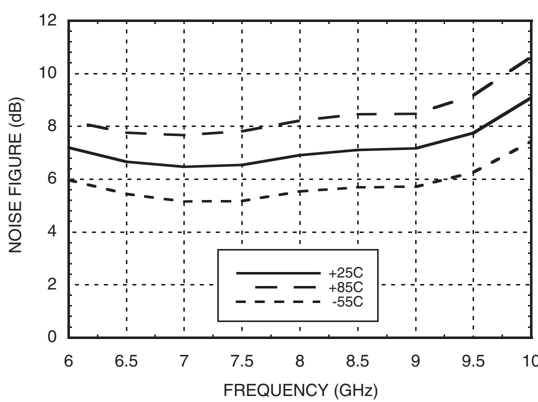
Gain, Power & Output IP3 vs. Supply Voltage @ 8 GHz



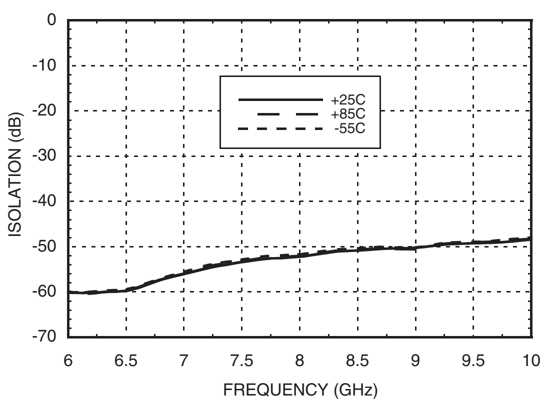
Gain, Power & Output IP3 vs. Supply Current @ 8 GHz



Noise Figure vs. Temperature



Reverse Isolation vs. Temperature



For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
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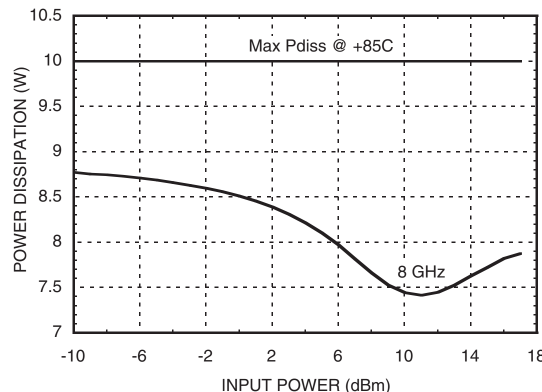
GaAs PHEMT MMIC 2 WATT POWER AMPLIFIER, 7 - 9 GHz

Power Dissipation



Absolute Maximum Ratings

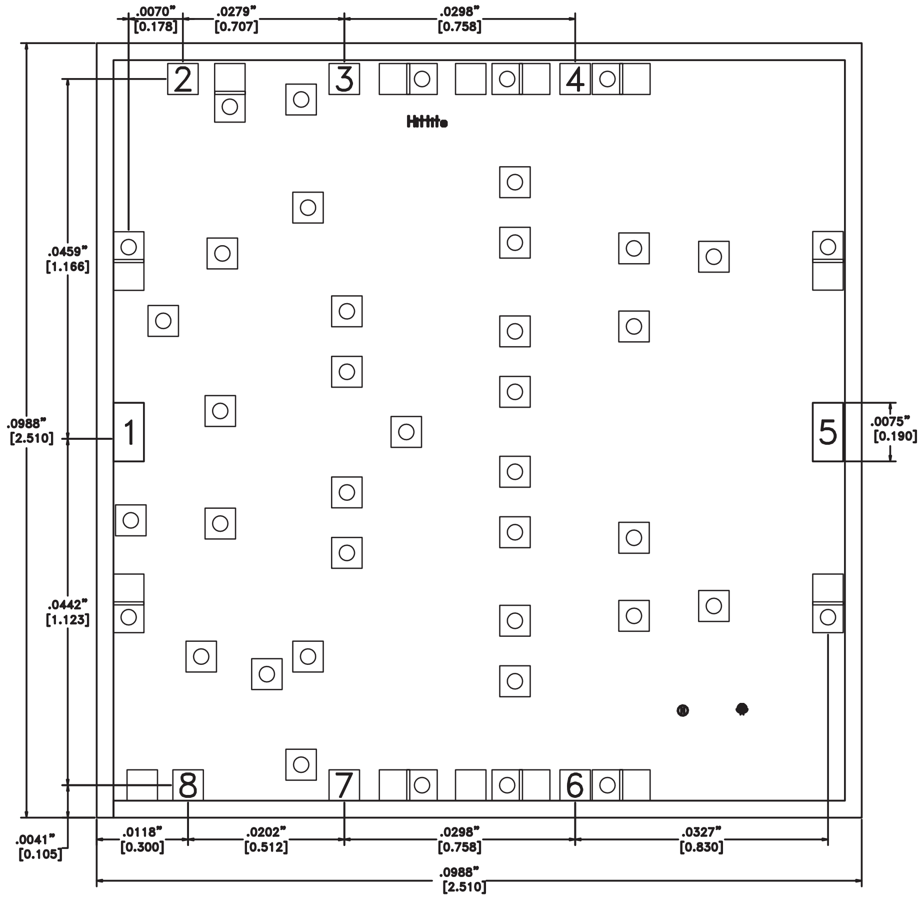
Drain Bias Voltage (Vdd)	+8 Vdc
Gate Bias Voltage (Vgg)	-2 to 0 Vdc
RF Input Power (RFIN)(Vdd = +7 Vdc)	+15 dBm
Channel Temperature	175 °C
Continuous Pdiss (T= 85 °C) (derate 105 mW/°C above 85 °C)	9.45 W
Thermal Resistance (channel to die bottom)	9.5 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Typical Supply Current vs. Vdd

Vdd (V)	Idd (mA)
+6.5	1305
+7.0	1300
+7.5	1295

Note: Amplifier will operate over full voltage ranges shown above Vgg adjusted to achieve Idd = 1300 mA at +7.0V

Outline Drawing



Die Packaging Information [1]

Standard	Alternate
GP-1 (Gel Pack)	[2]

[1] Refer to the "Packaging Information" section for die packaging dimensions.
[2] For alternate packaging information contact Hittite Microwave Corporation.

NOTES:
1. ALL DIMENSIONS ARE IN INCHES [MM]
2. DIE THICKNESS IS .004"
3. TYPICAL BOND PAD IS .004" SQUARE
4. BACKSIDE METALLIZATION: GOLD
5. BOND PAD METALLIZATION: GOLD
6. BACKSIDE METAL IS GROUND.
7. CONNECTION NOT REQUIRED FOR UNLABELED BOND PADS.
8. OVERALL DIE SIZE ± .002

Pad Descriptions

Pad Number	Function	Description	Interface Schematic
1	RFIN	This pad is AC coupled and matched to 50 Ohms.	RFIN
2 - 4, 6, 7	Vdd 1-5	Power Supply Voltage for the amplifier. External bypass capacitors of 100 pF and 0.1 μF are required.	Vdd1−5
5	RFOUT	This pad is AC coupled and matched to 50 Ohms.	RFOUT
8	Vgg	Gate control for amplifier. Adjust to achieve Idd of 1300 mA. Please follow "MMIC Amplifier Biasing Procedure" Application Note. External bypass capacitors of 100 pF and 0.1 μF are required.	Vgg
Die Bottom	GND	Die bottom must be connected to RF/DC ground.	GND

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Assembly Diagram

Mounting & Bonding Techniques for Millimeterwave GaAs MMICs

The die should be attached directly to the ground plane eutectically or with conductive epoxy (see HMC general Handling, Mounting, Bonding Note).

50 Ohm Microstrip transmission lines on 0.127mm (5 mil) thick alumina thin film substrates are recommended for bringing RF to and from the chip (Figure 1). If 0.254mm (10 mil) thick alumina thin film substrates must be used, the die should be raised 0.150mm (6 mils) so that the surface of the die is coplanar with the surface of the substrate. One way to accomplish this is to attach the 0.102mm (4 mil) thick die to a 0.150mm (6 mil) thick molybdenum heat spreader (moly-tab) which is then attached to the ground plane (Figure 2).

Microstrip substrates should be located as close to the die as possible in order to minimize bond wire length. Typical die-to-substrate spacing is 0.076mm to 0.152 mm (3 to 6 mils).

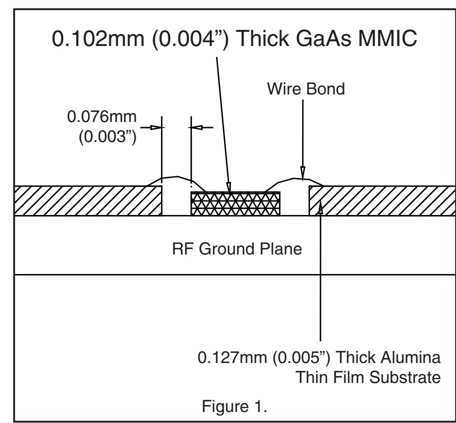

Figure 1.

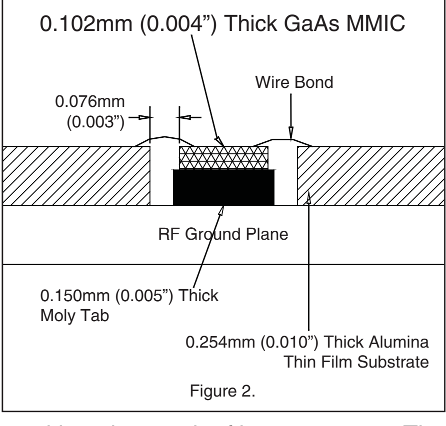

Figure 2.

Handling Precautions

Follow these precautions to avoid permanent damage.

Storage: All bare die are placed in either Waffle or Gel based ESD protective containers, and then sealed in an ESD protective bag for shipment. Once the sealed ESD protective bag has been opened, all die should be stored in a dry nitrogen environment.

Cleanliness: Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

Static Sensitivity: Follow ESD precautions to protect against ESD strikes.

Transients: Suppress instrument and bias supply transients while bias is applied. Use shielded signal and bias cables to minimize inductive pick-up.

General Handling: Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers. The surface of the chip may have fragile air bridges and should not be touched with vacuum collet, tweezers, or fingers.

Mounting

The chip is back-metallized and can be die mounted with electrically conductive epoxy. The mounting surface should be clean and flat.

Epoxy Die Attach: Apply a minimum amount of epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip once it is placed into position. Cure epoxy per the manufacturer’s schedule.

Wire Bonding

Ball or wedge bond with 0.025mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31mm (12 mils).